

## SPECIFICATION

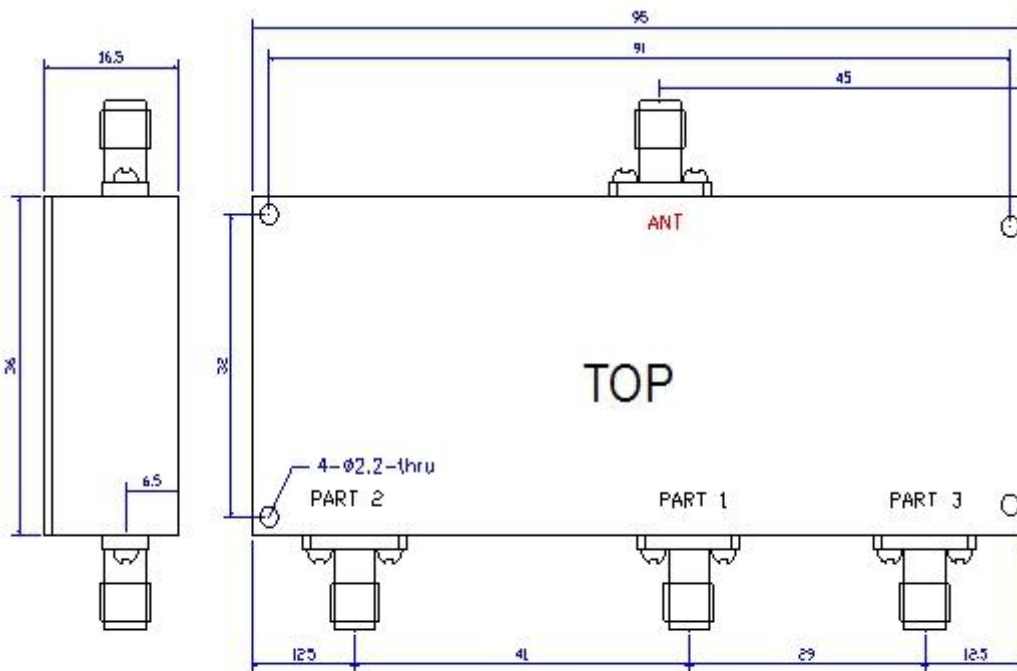
Part No.: \_\_\_\_\_  
Customer: \_\_\_\_\_  
Date: \_\_\_\_\_

Written by	Checked by	Approval
FL Lai	PH Jiang	CK Chang

### ELECTRICAL SPECIFICATIONS

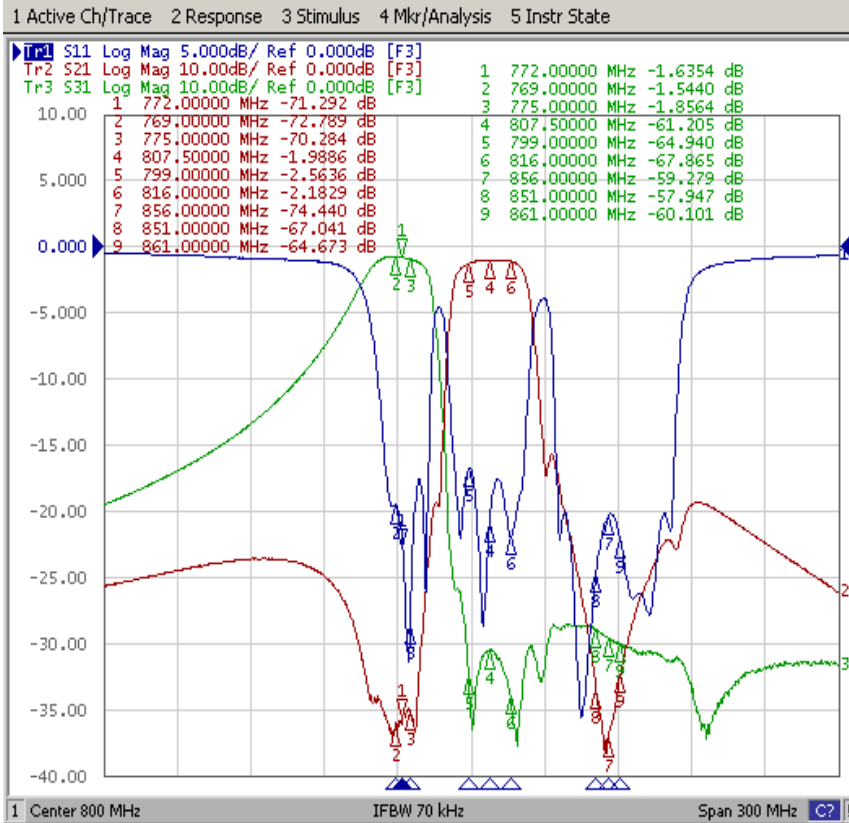
ITEM	Part 1	Part 2	Part 3	UNIT	
1	Center freq	772	807.5	856	MHz
2	Bandwidth [BW]	fo ±3 [769.0~775.0]	fo ±8.5[799.0~816.0]	fo ±5[851.0~861.0]	MHz
3	Insertion Loss in BW	3.0	3.0	3.0	dB max
4	Ripple in BW	1.0	1.0	1.0	dB max
5	VSWR in BW@ANT	1.5	1.5	1.5	max
6	Attenuation	50 min. @ [799~816] 50 min. @ [851~861]	60 min. @ [769~775] 50 min. @ [851~861]	60 min. @ [769~775] 60 min. @ [799~816]	dB min
7	Group Delay Variation				ns max
8	Input Power	3.0			W
9	In/Out Impedance	50Ω			Ω
10	Operation Temperature Range	-40°C to +85°C			°C

### MECHANICAL SPECIFICATIONS

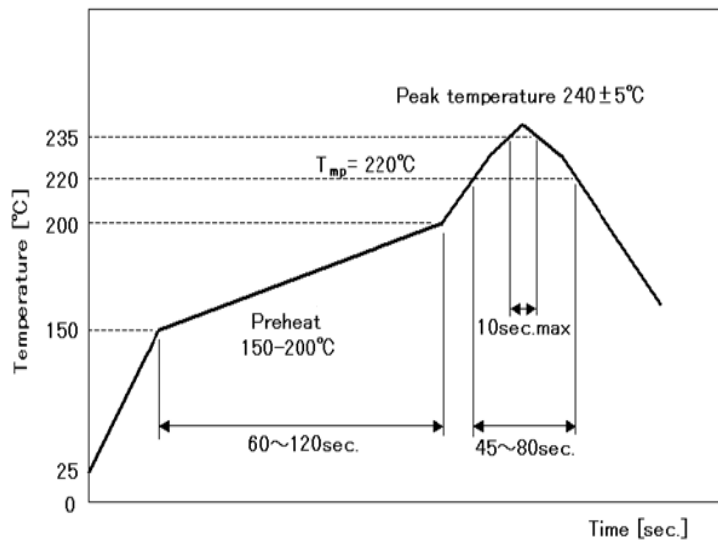


TOL:±0.2  
UNIT:mm

### PERFORMANCE



### SOLDERING CONDITION



Remark:

1. Please ensure that the good grounding (ground and I/O part area). When the product is used, in order to ensure good grounding ,bottom area after soldering, that need for the side pin to repair welding.
2. Product recommended using SMT process, the above is recommended reflow temperature curve. Because of different substrate and reflow soldering equipment varies , according to the substrate and reflow soldering equipment to confirm the actual temperature curve.
3. If special occasion occurs which needs manual soldering, the temperature should be  $350^\circ\text{C}$  ,but not Over 3 times, and reflow and manual soldering should not be over 3 times.